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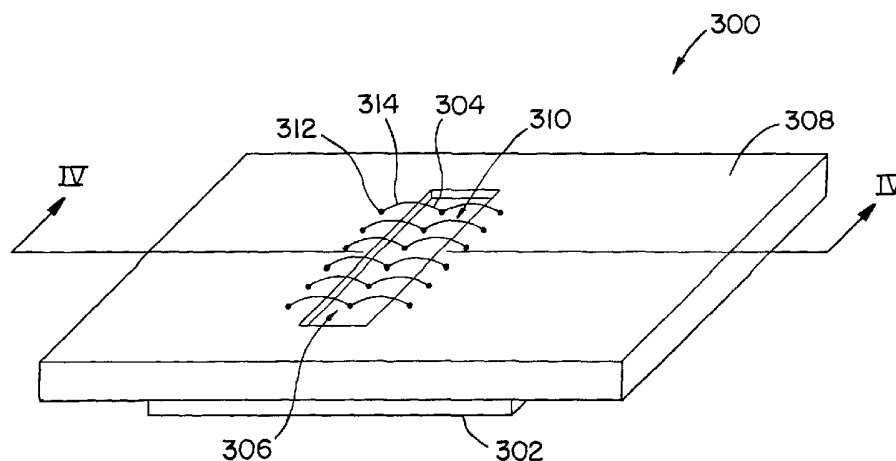
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(54) Title: ELECTRONIC COMPONENT PACKAGING



(57) Abstract: An electronic component package and a method of forming the package are disclosed. The package includes a die (302) having a top face with set of contacts and a substrate (308) having a cutout (310) therein. The die (302) may include a memory component and may include SDRAM. The substrate (308) is mounted on the top face, and the cutout (310) overlays the set of contacts. Wire leads (314) extend from the set of contacts, at least partially through the cutout (310), to the substrate (308). The set of contacts may be positioned along a central region of the die (302), and the cutout (310) overlays the central region. The wire leads (314) extend to the substrate (308) and may contact the substrate proximate to the cutout. The package may further include a set of electrical paths extending from the wire leads (314) through the substrate (308) for providing communicative path between the die and an external component.

WO 2004/100219 A3



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B. FIELDS SEARCHED
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Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched
 NONE

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)
 EAST

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 6,091,140 A (TOH et al) 18 July 2000 (18.07.2000), Figure 4, column 5, lines 40-62, and column 6, lines 5-37.	1-26

Further documents are listed in the continuation of Box C. See patent family annex.

* Special categories of cited documents:	"T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention
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